

QIAOXIN N-Channel Enhancement Mode Power MOSFET

Description

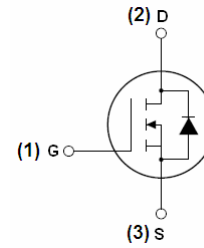
The VCRR60H10F uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Feature

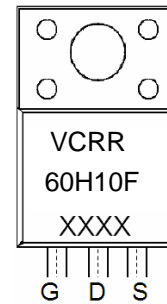
- $V_{DS} = 60V, I_D = 100A$
 $R_{DS(ON)} < 6.5m\Omega @ V_{GS}=10V$ (Typ:5.7m Ω)
- Special process technology for high ESD capability
- High density cell design for ultra low R_{dson}
- Fully characterized Avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation

Application

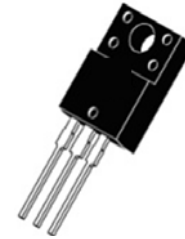
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Schematic diagram



Marking and pin assignment



TO-220F top view

Package Marking and Ordering Information

Device Marking	Device	Device Package
VCRR60H10F		TO-220F

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous	I_D	100	A
Drain Current-Continuous($T_C=100^\circ C$)	$I_D(100^\circ C)$	70	A
Pulsed Drain Current	I_{DM}	320	A
Maximum Power Dissipation	P_D	45	W
Derating factor		0.3	W/ $^\circ C$
Single pulse avalanche energy ^(Note 5)	E_{AS}	550	mJ
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 175	$^\circ C$

Thermal Characteristic

Thermal Resistance, Junction-to-Case ^(Note 2)	$R_{\theta JC}$	3.3	$^{\circ}C/W$
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Electrical Characteristics ($T_C=25^{\circ}C$ unless otherwise noted)

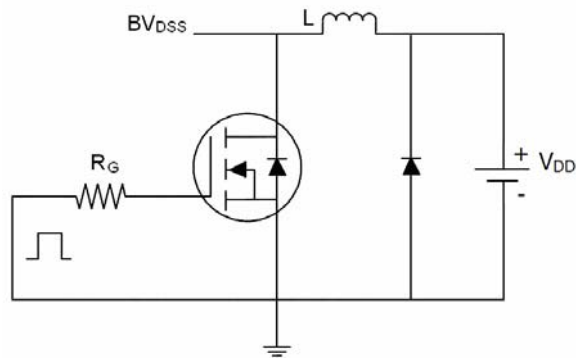
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	60	65	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60V, V_{GS}=0V$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
On Characteristics ^(Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3	4	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=40A$	-	5.7	6.5	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=10V, I_D=40A$	-	50	-	S
Dynamic Characteristics ^(Note 4)						
Input Capacitance	C_{iss}	$V_{DS}=30V, V_{GS}=0V,$ $F=1.0MHz$	4037	4750	5460	PF
Output Capacitance	C_{oss}		336	396	455	PF
Reverse Transfer Capacitance	C_{rss}		260	339	389	PF
Switching Characteristics ^(Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=30V, V_{GS}=10V, R_{GEN}=2.5\Omega$	-	16.8	-	nS
Turn-on Rise Time	t_r		-	10.8	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	55	-	nS
Turn-Off Fall Time	t_f		-	13.6	-	nS
Total Gate Charge	Q_g	$V_{DS}=30V, I_D=40A,$ $V_{GS}=10V$	-	94.8	-	nC
Gate-Source Charge	Q_{gs}		-	17.3	-	nC
Gate-Drain Charge	Q_{gd}		-	33.8	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage ^(Note 3)	V_{SD}	$V_{GS}=0V, I_S=40A$	-	-	1.2	V
Diode Forward Current ^(Note 2)	I_S	-	-	-	90	A
Reverse Recovery Time	t_{rr}	$T_J = 25^{\circ}C, I_F = 40A$ $di/dt = 100A/\mu s$ ^(Note 3)	-	38	-	nS
Reverse Recovery Charge	Q_{rr}		-	53	-	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

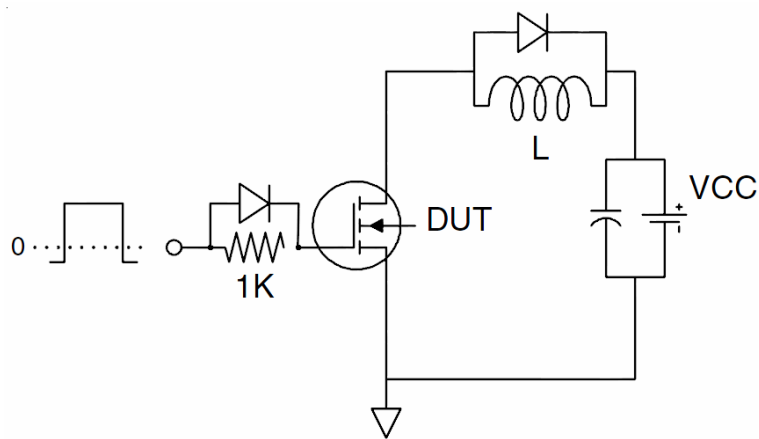
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_J=25^{\circ}C, V_{DD}=30V, V_G=10V, L=0.5mH, R_g=25\Omega$

Test circuit

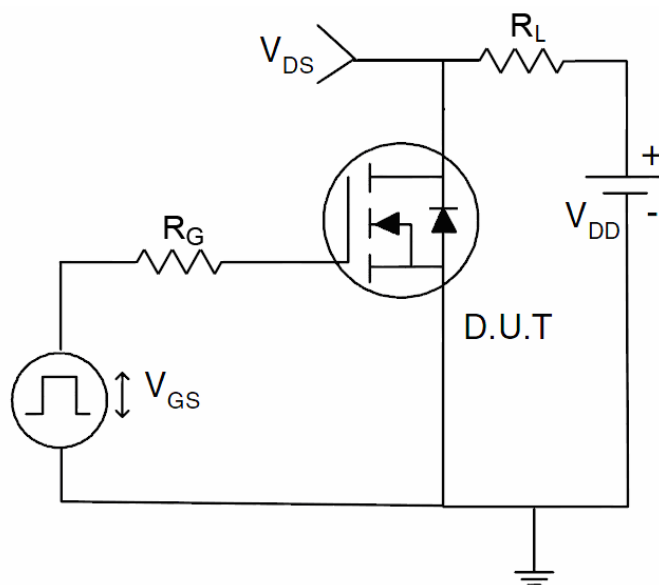
1) E_{AS} test Circuits



2) Gate charge test Circuit:



3) Switch Time Test Circuit:



Typical Electrical and Thermal Characteristics (Curves)

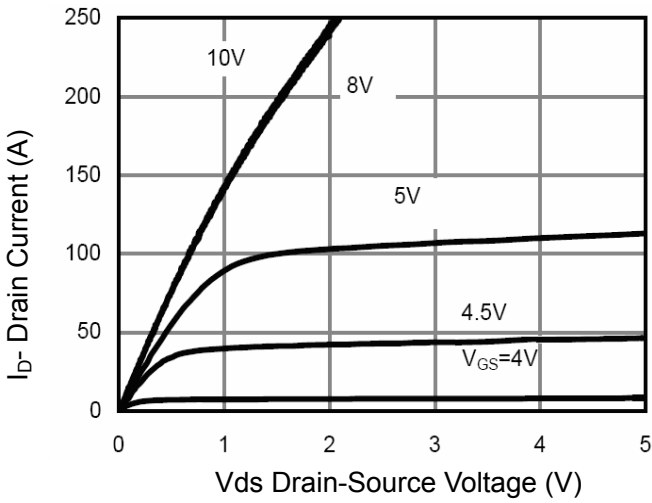


Figure 1 Output Characteristics

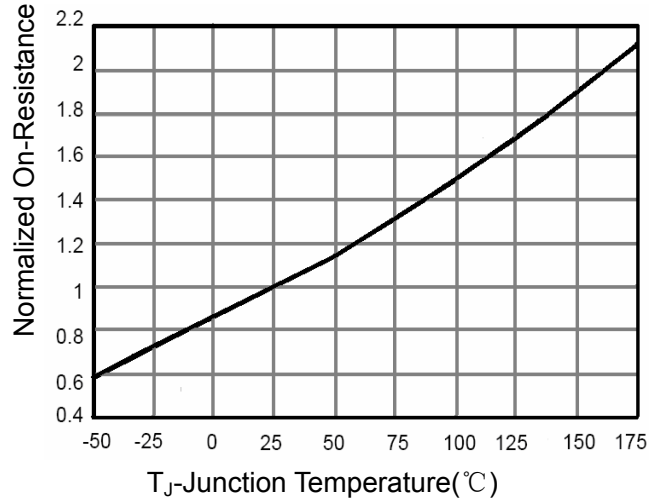


Figure 4 Rdson-Junction Temperature

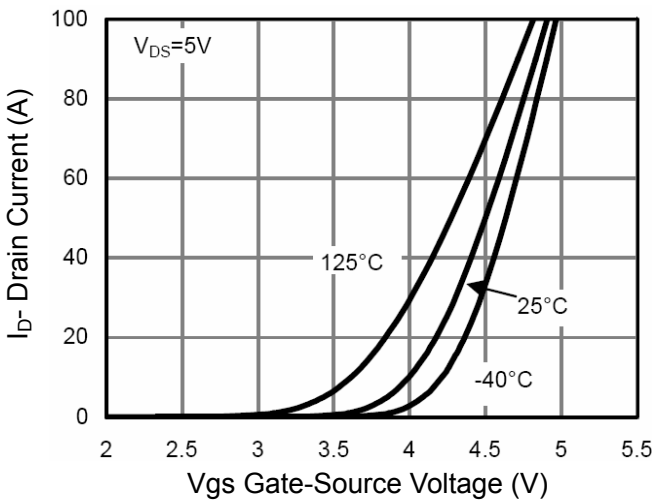


Figure 2 Transfer Characteristics

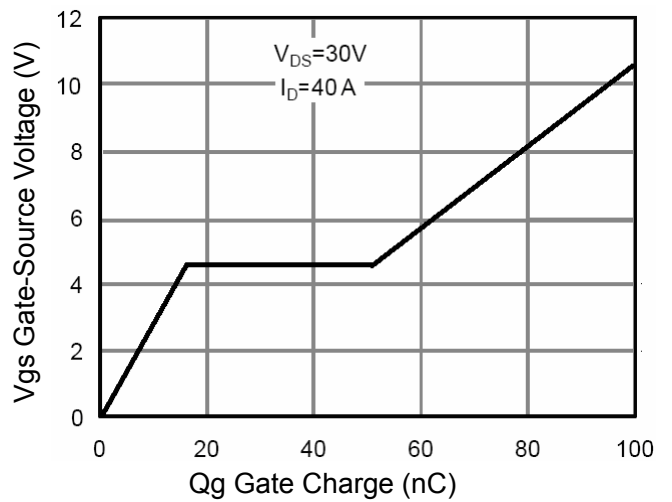


Figure 5 Gate Charge

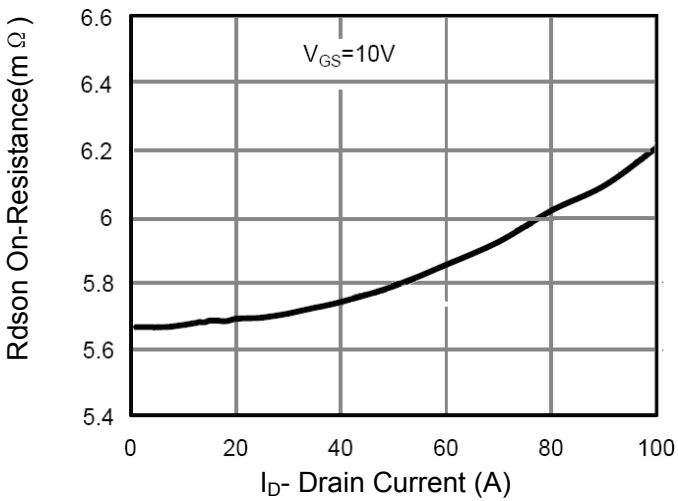


Figure 3 Rdson- Drain Current

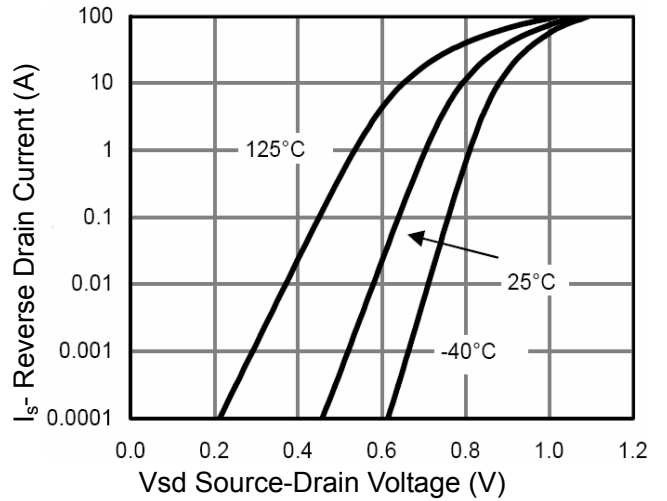


Figure 6 Source- Drain Diode Forward

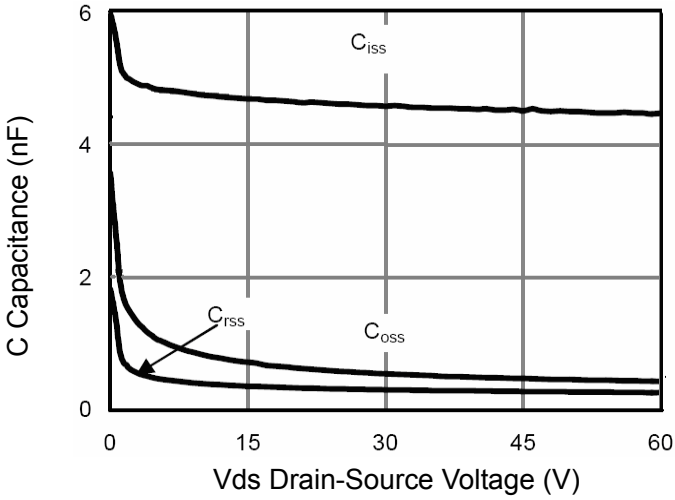


Figure 7 Capacitance vs Vds

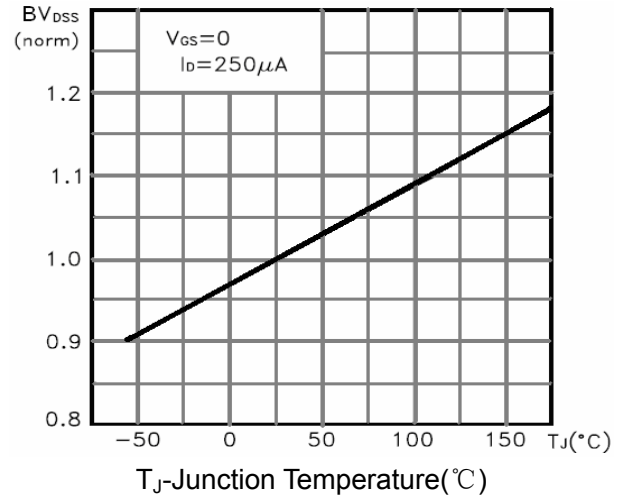


Figure 9 BV_{DSS} vs Junction Temperature

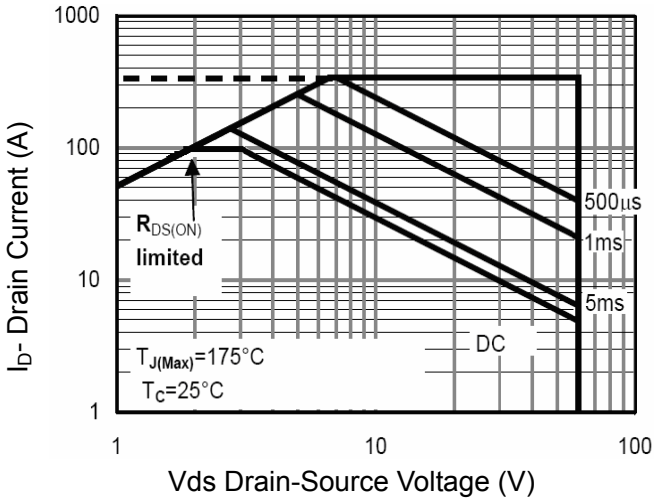


Figure 8 Safe Operation Area

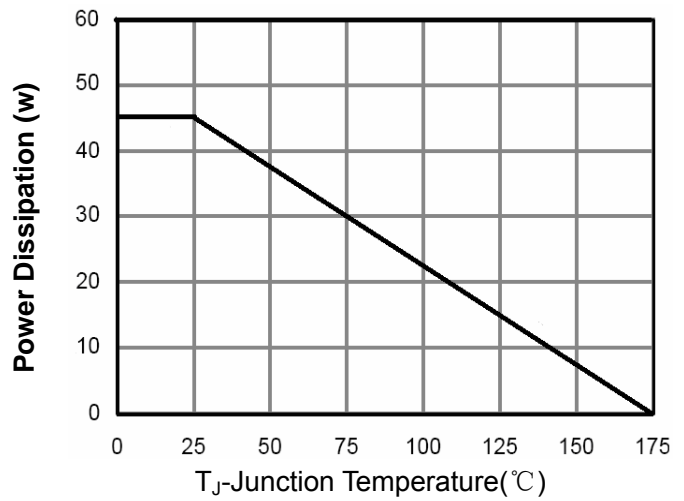


Figure 10 Power De-rating

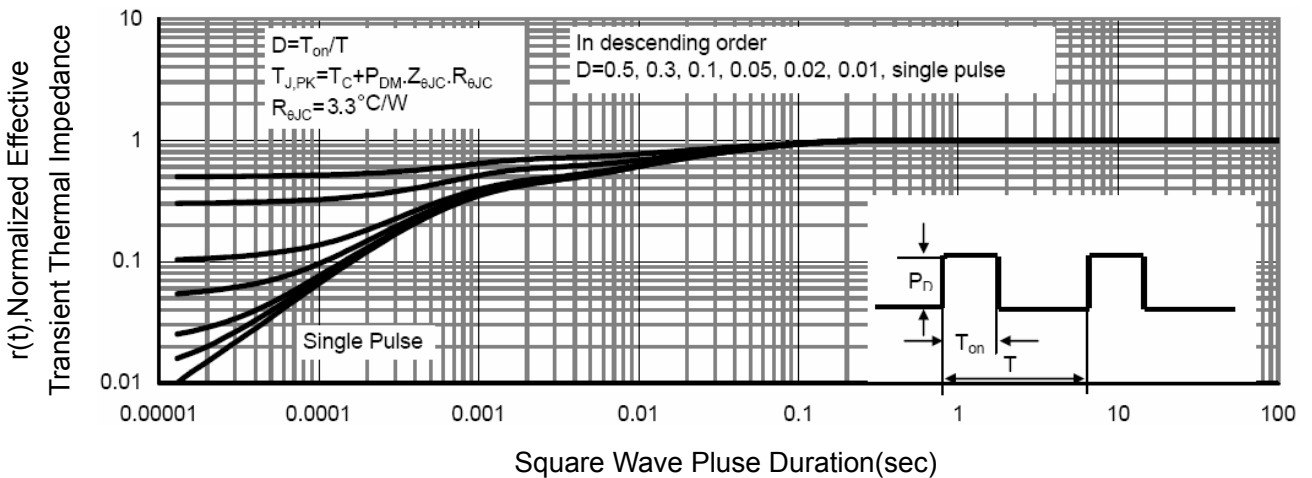
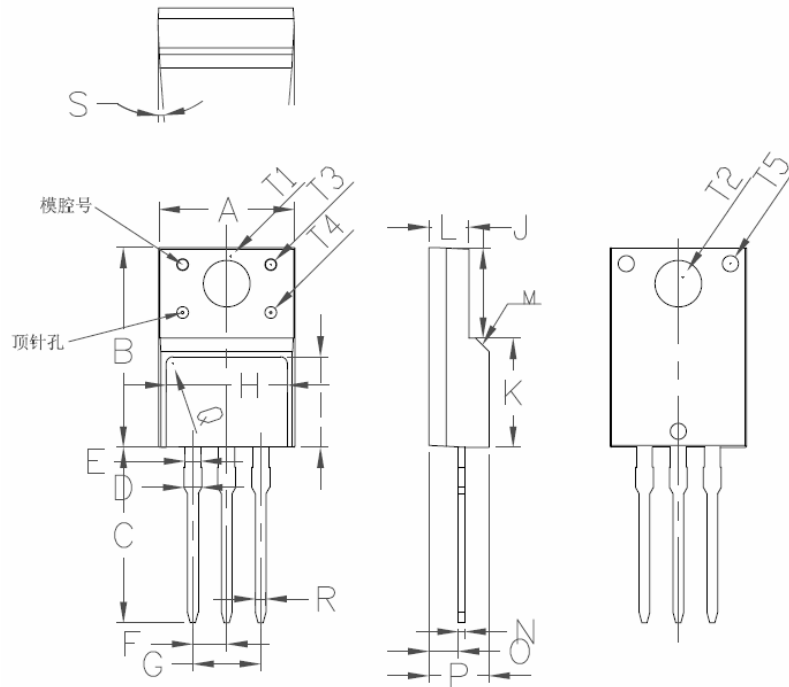


Figure 11 Normalized Maximum Transient Thermal Impedance

TO-220F Package Information



Symbol	Dimensions In Millimeters		
	Min.	Non	Max.
A	9.96	10.16	10.36
B	15.67	15.87	16.07
C	13.14	13.34	13.54
D	1.20	1.30	1.40
E		1.20	
F		2.54	
G		5.08	
H	7.60	7.80	8.00
I	7.10	7.30	7.50
J	6.48	6.68	6.88
K	8.99	9.19	9.39
L	2.34	2.54	2.74
N	0.49	0.50	0.52
O	2.15	2.35	2.55
P	4.50	4.70	4.90
T1		3.45	
T2		3.18	
T3		1.50	
T4		1.20	
T5		1.50	
R	0.77	0.80	0.83

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